

Improvements from V0.1:

- Fixed GND vias for USB port (some were not named as GND and left isolated)
- Add in silkscreen for input + output header pins (clearer for users)
- Spaced out USB ports to have 6mm distance in between (support more devices)
- increased thickness for most power traces (improve power dissipation)
- Increase Isolate to 15mil for 5V plane (increase manufacturability)
- Added bStop for USB pads! (expose the USB pins on bottom layer)
- version silkscreen on pcb to v0.2

